



SOT435-1

plastic low profile quad flat package; 160 leads; body 24 x 24 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP160
Package type industry code	LQFP160
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		23.9	-	24	24.1	mm
E	package width		23.9	-	24	24.1	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination		-	-	160	-	



2. Package outline

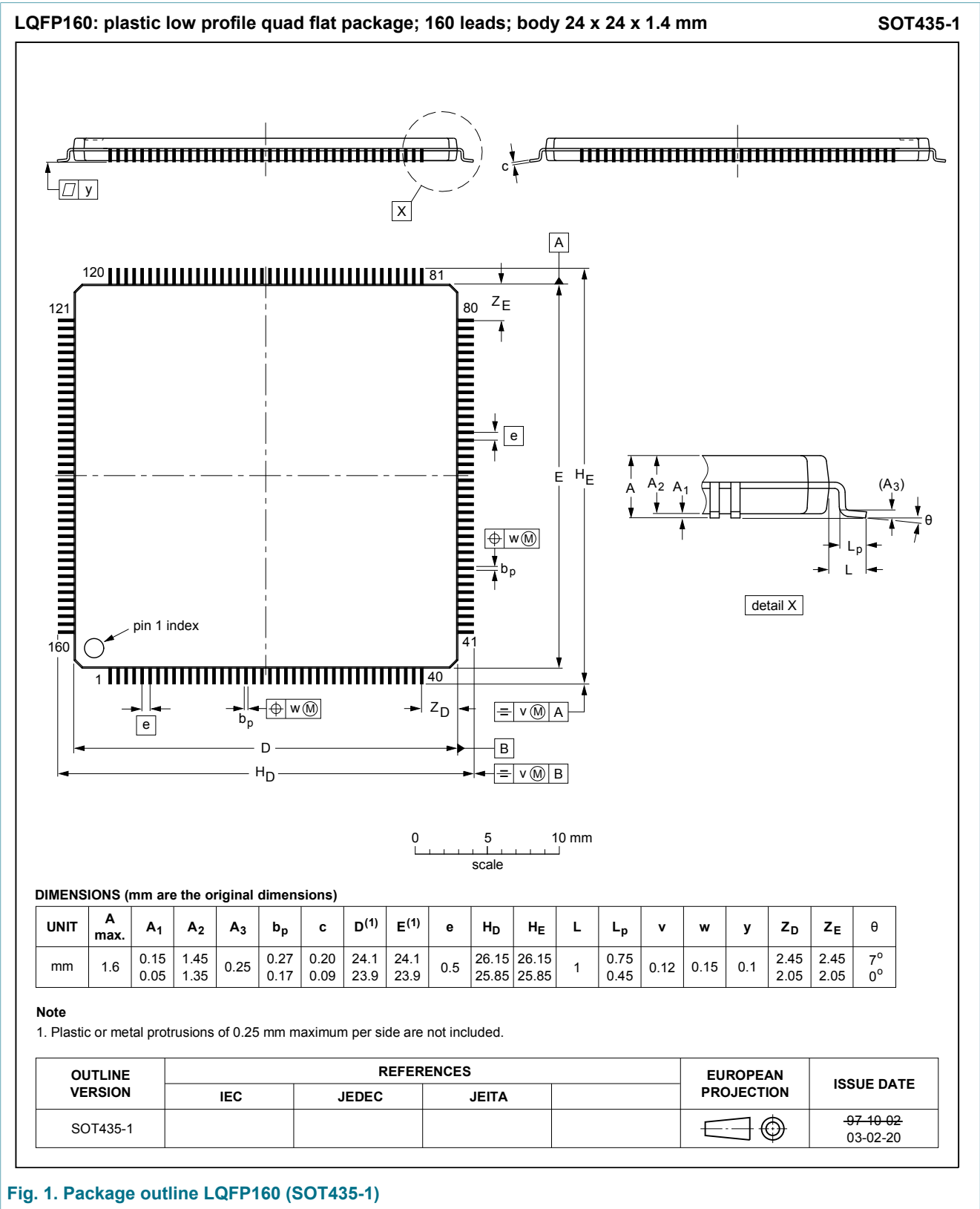


Fig. 1. Package outline LQFP160 (SOT435-1)

3. Soldering

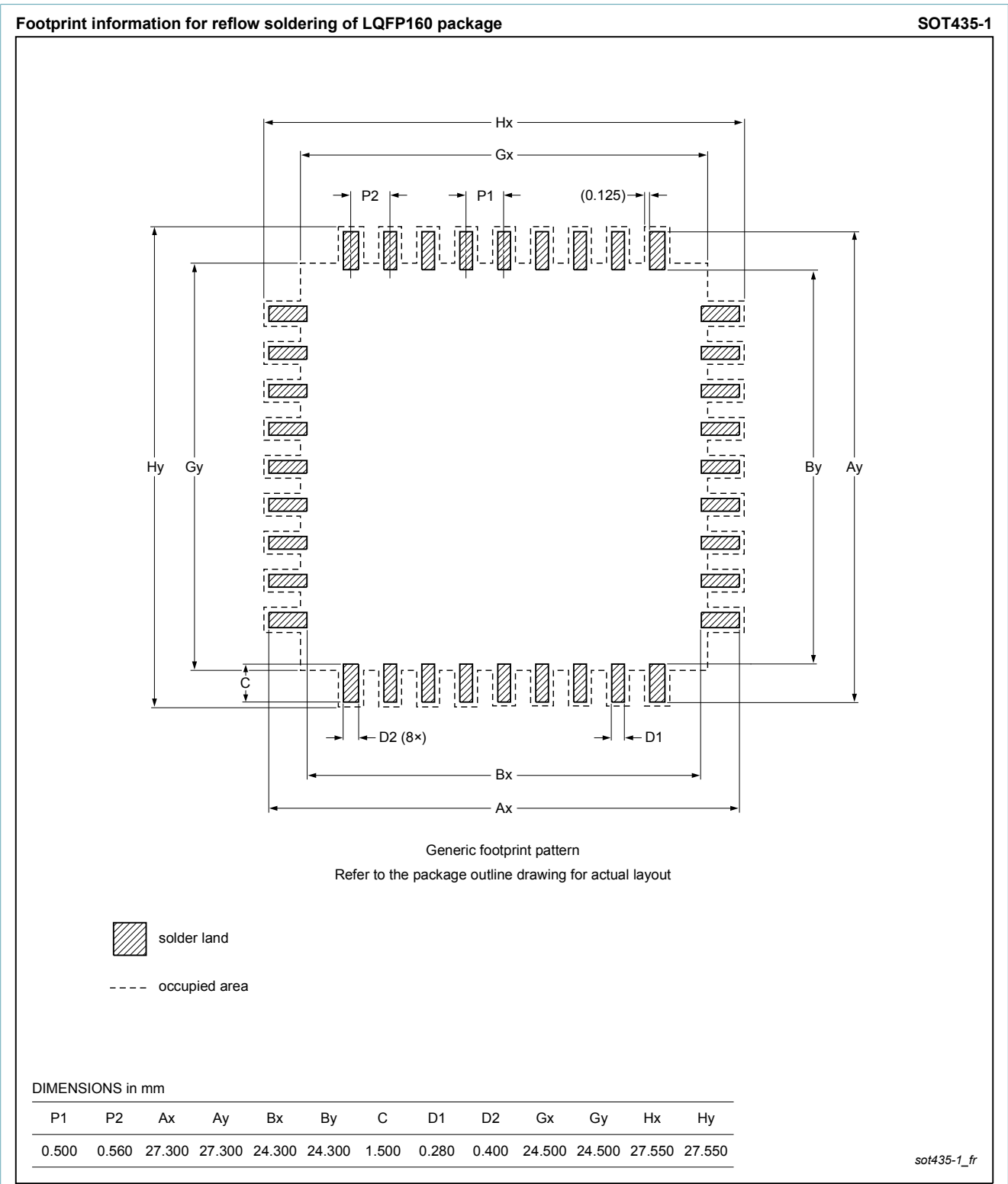


Fig. 2. Reflow soldering footprint for LQFP160 (SOT435-1)

4. Legal information

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